



CBR-SMD RF COG, Ceramic, 2.5 pF, +/-0.05 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information		
Series	CBR-SMD RF COG	
Style	SMD Chip	
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I	
Features	Ultra High Q, Low ESR, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	1.37 mg	
Notes	Solder Reflow Only.	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

Т	0.5mm +/-0.05mm	Dielectric Withstanding
В	0.25mm +0.05/-0.1mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Dissipation Factor
Packaging	T&R, 180mm, Plastic Tape	Aging Rate
Packaging Quantity	10000	Insulation Resistance

Specifications	
Capacitance	2.5 pF
Tolerance	+/-0.05 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.222%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	450

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